

PATENT ABSTRACTS OF JAPAN

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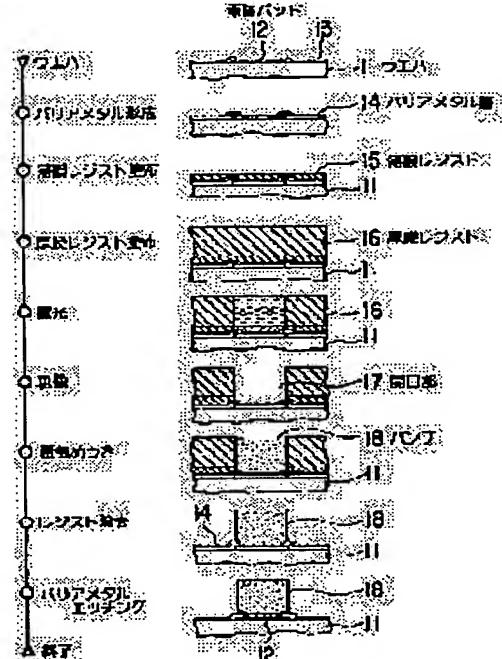
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(54) METHOD OF MANUFACTURING BUMP STRUCTURE

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a method of bump forming capable of controlling plating easily without growth of a plating film at the boundary face with a barrier metal layer in a process of plating which forms bump, preventing contamination of plating solution and short circuits between the electrodes.

SOLUTION: First, a thin film resist 15 is applied to a barrier metal layer 14 in a process of forming a bump 18 on a electrode pad 12 on a water 11 through a barrier metal layer 14. Second, a thick film resist 16 is applied to the thin film resist 15. Third, the electrode pad 12 is exposed by removing the thin film resist 15 and the thick film resist 16 opposed to the electrode pad 12. The bump 18 is formed on the exposed electrode pad 12 by plating.



LEGAL STATUS

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